WHAT IS CLAIMED IS:

1. A contact pad for a circuit board, the contact pad comprising:

a central portion; and

a plurality of spokes extending from the central portion.

2. The contact pad of claim 1, wherein the central portion is substantially circular.

3. The contact pad of claim 1, wherein each of the plurality of spokes is substantially rectangular in shape.

4. The contact pad of claim 1, wherein one of the plurality of spokes is electrically connected to a metallic trace on the circuit board.

5. The contact pad of claim 1, wherein the circuit board is a printed circuit board.

6. The contact pad of claim 1, wherein there are four spokes extending radially outwardly from the substantially circular portion.

7. The contact pad of claim 1, wherein the plurality of spokes are substantially evenly spaced around the substantially circular portion.

8. The contact pad of claim 1, further comprising a solder mask at outer tips of the spokes.

9. The contact pad of claim 1, wherein contact pad is made of a conductive material.

10. A contact pad for a circuit board, the contact pad comprising:

a central portion; and

means extending from the central portion for providing additional surface area of the contact pad to which a solder ball may attach.

11. The contact pad of claim 10, wherein the central portion includes an opening in a center thereof.

12. A contact pad for a circuit board, the contact pad comprising:

a substantially circular portion; and

means extending from the substantially circular portion for providing additional surface area of the contact pad to which a solder ball may attach.

13. The contact pad of claim 12, wherein the substantially circular portion includes an opening in a center thereof.

14. A circuit board, comprising:

a nonconductive substrate;

a plurality of electrically conductive contact pads, each of the contact pads having a central portion; and a plurality of spokes extending from the central portion; and

an electrically conductive trace interconnecting the contact pads.

15. The circuit board of claim 14, wherein the central portion is substantially circular.

16. The circuit board of claim 14, wherein each of the plurality of spokes is substantially rectangular in shape.

17. The circuit board of claim 14, wherein one of the plurality of spokes is electrically connected to the trace on the circuit board.

18. The circuit board of claim 14, wherein the circuit board is a printed circuit board.

19. The circuit board of claim 14, wherein each of the contact pads has four spokes extending radially outwardly from the substantially circular portion.

20. The circuit board of claim 14, wherein on at least one of the contact pads, the plurality of spokes are substantially evenly spaced around the substantially circular portion.

21. A contact pad for a circuit board, the contact pad comprising a conductive material arranged in a shape having a perimeter that is at least 5% longer in length than a circumference of a circle having a diameter that is equal to a distance between the two points on the perimeter of the contact pad that are farthest away from each other.

22. The contact pad of claim 21, wherein the perimeter is at least 10% longer than the diameter.

23. The contact pad of claim 21, wherein the perimeter is at least 15% longer than the diameter.

24. The contact pad of claim 21, wherein the perimeter is at least 20% longer than the diameter.

25. The contact pad of claim 21, wherein the perimeter is at least 30% longer than the diameter.